a1 preferably 2% or less, still preferably 1% or less. Numerals 21 and 22 are a pressure-sensitive adhesive layer and a substrate, respectively.

Page 3 of the specification, paragraph 3, please delete that paragraph and add the following new paragraph:

In producing resin-encapsulated semiconductor chips according to the present invention, semiconductor chips 3 are placed and fixed in the device holes, one by one, of the leadframe 1 a2 with the pressure-sensitive adhesive tape adhered thereto, and the chip 3 and the stitches 11 of the leadframe 1 are bonded with a bonding wire 31 as shown in Fig. 1B. In Fig. 1B, numeral 2 shows a pressure-sensitive adhesive tape including a pressure-sensitive adhesive layer 21 and a substrate 22, respectively, in the same manner as in Fig. 1A. In the step of resin encapsulating, the semiconductor chip 3 is placed in each cavity 41 of a mold 4 and encapsulated with a resin by transfer molding as shown in Fig. 1C. Then as shown in Fig. 1D, the pressure-sensitive adhesive tape is stripped off the leadframe 1, and the leadframe is cut and trimmed to obtain a resin-encapsulated semiconductor chip shown in Fig. 1E.

IN THE CLAIMS:

Please enter the following amended claims:

3. (Amended) A pressure-sensitive adhesive tape to be adhered to a leadframe, which can be used in the resin encapsulating method for a semiconductor chip according to claim 1 or 2 and has a thermal shrinkage of 3% or less and a pressure-sensitive adhesive strength of 400 gf/20 mm or less at 23°C on resin encapsulating.

Please add the following new claims: